



SOT266-1

plastic shrink small outline package; 20 leads; body width 4.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP20
Package type industry code	SSOP20
Package style descriptive code	SSOP (shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-152
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.4	-	6.5	6.6	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	[tbd]	-	1.5	1.5	mm
A ₂	package height	1.2	-	1.25	1.4	mm
n ₂	actual quantity of termination	-	-	20	-	



2. Package outline

SSOP20: plastic shrink small outline package; 20 leads; body width 4.4 mm

SOT266-1

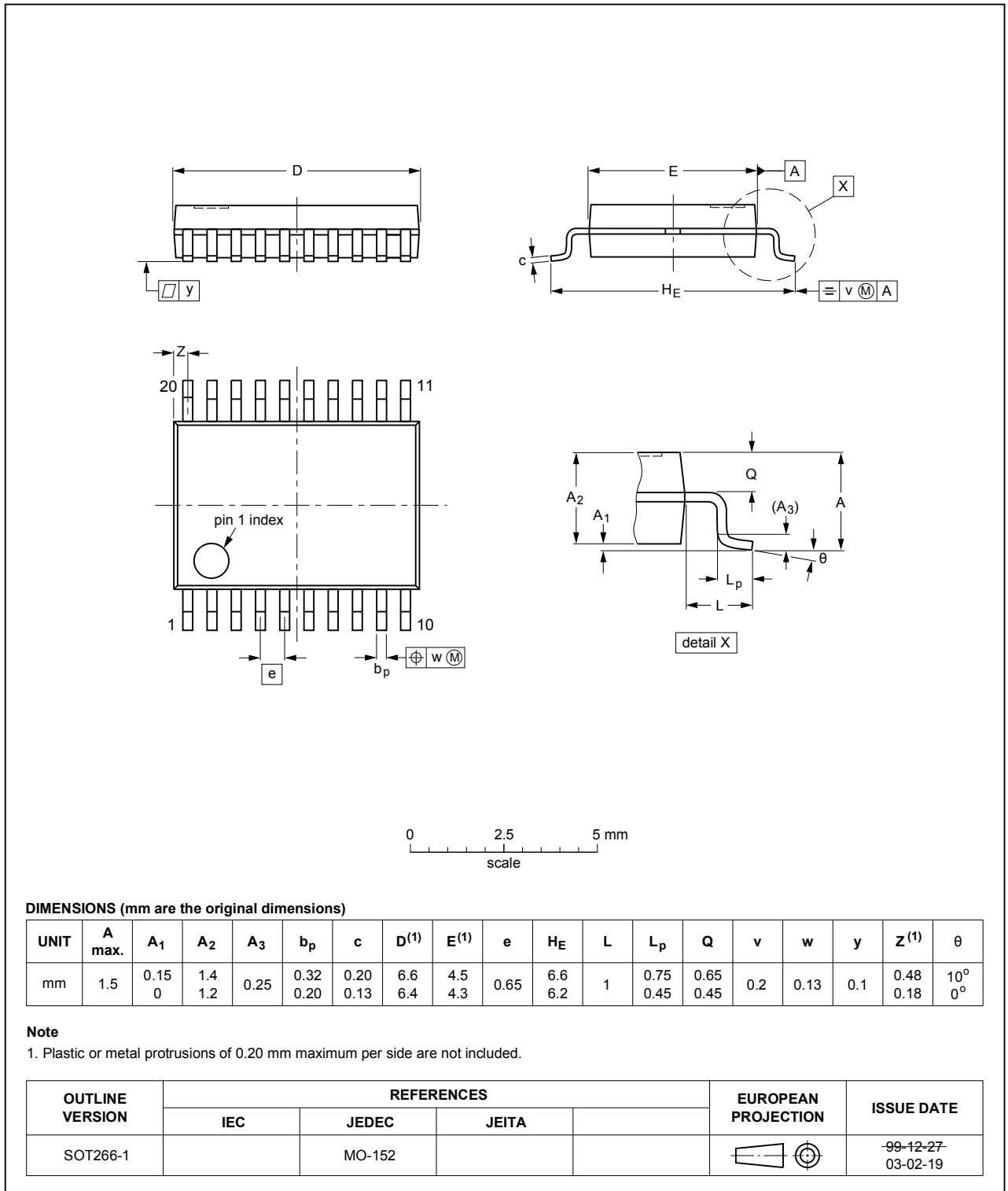


Fig. 1. Package outline SSOP20 (SOT266-1)

3. Soldering

Footprint information for reflow soldering of SSOP20 package SOT266-1

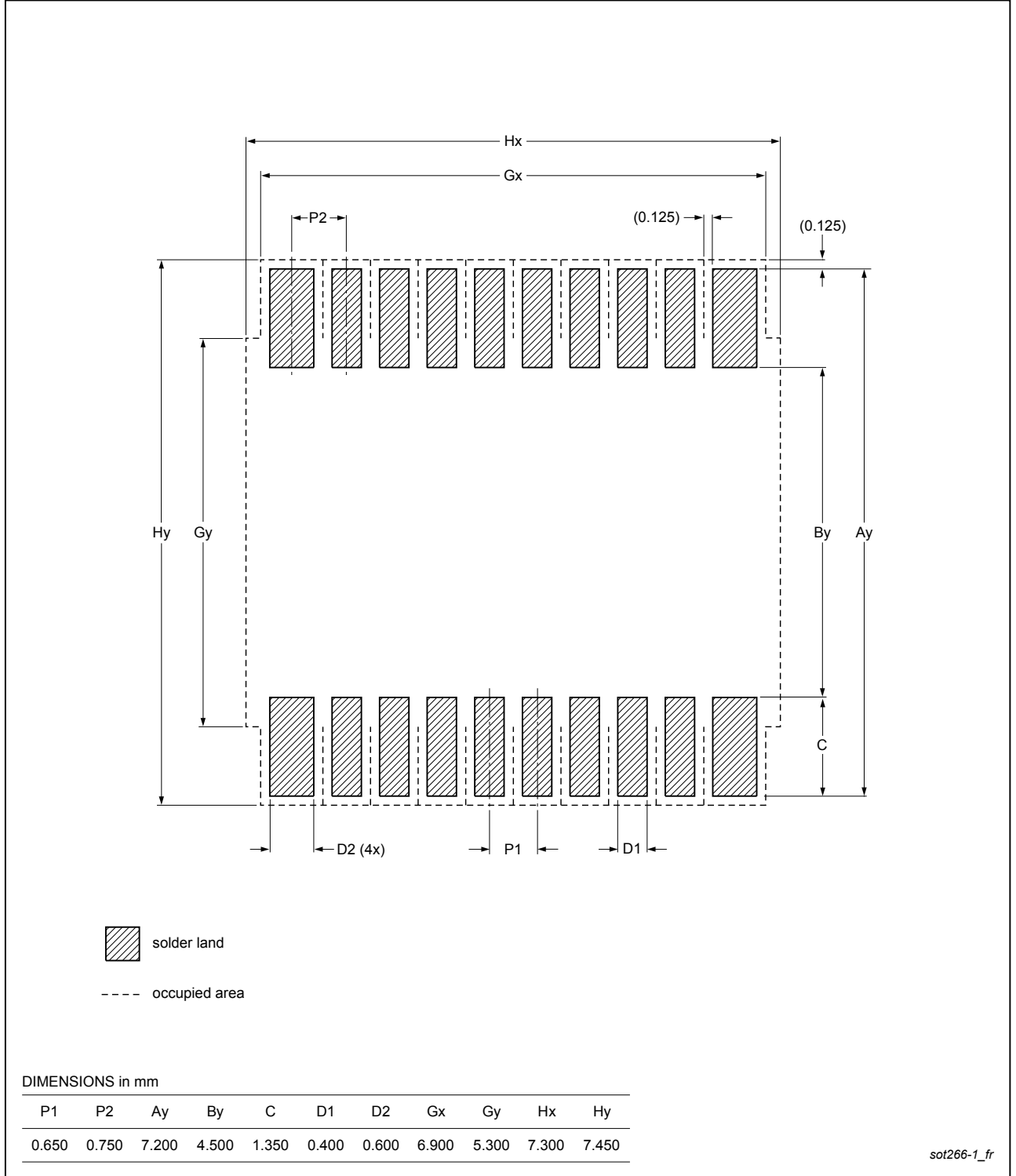


Fig. 2. Reflow soldering footprint for SSOP20 (SOT266-1)

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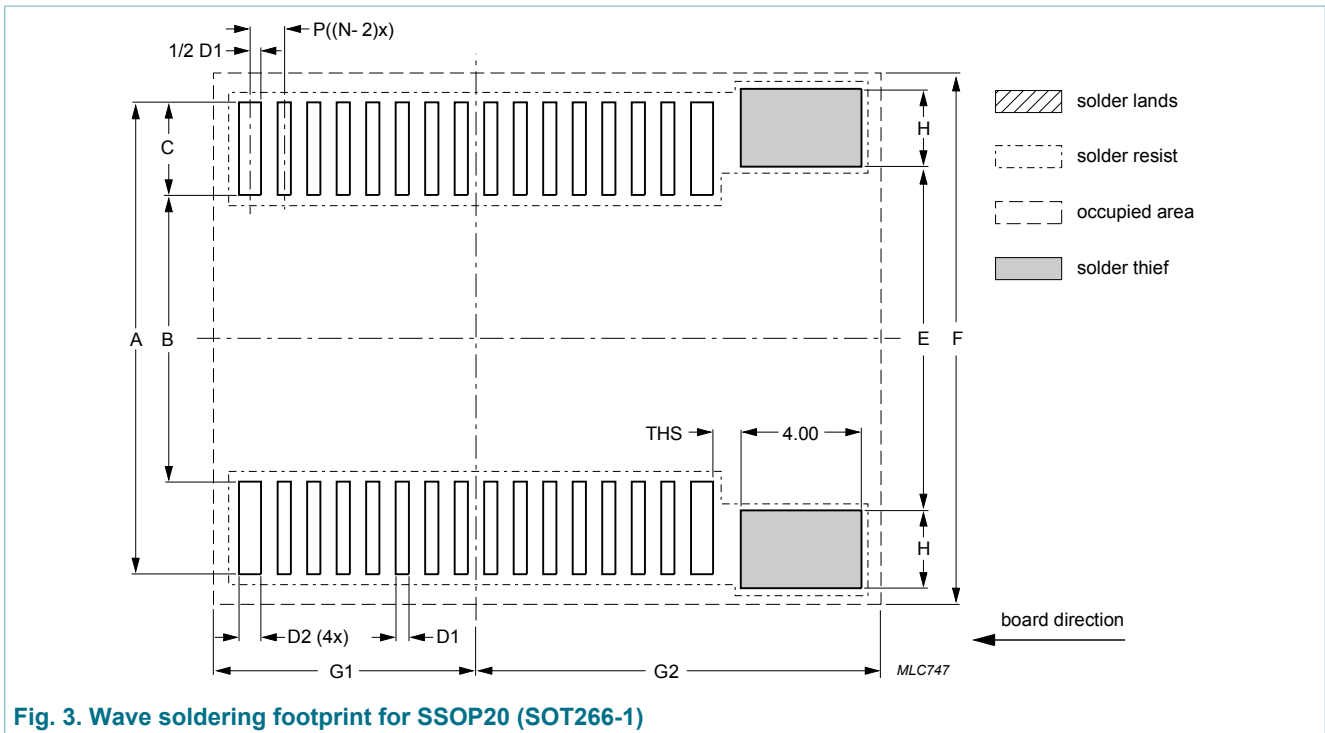


Fig. 3. Wave soldering footprint for SSOP20 (SOT266-1)

4. Legal information

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